

International IR Rectifier

RADIATION HARDENED POWER MOSFET THRU-HOLE (TO-257AA)

PD - 93827A

IRHY57230CM
200V, N-CHANNEL
R5 TECHNOLOGY



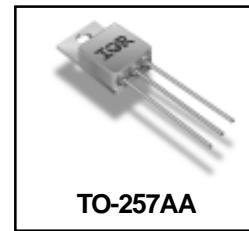
Product Summary

Part Number	Radiation Level	R _{Ds(on)}	I _D
IRHY57230CM	100K Rads (Si)	0.21Ω	12.5A
IRHY53230CM	300K Rads (Si)	0.21Ω	12.5A
IRHY54230CM	600K Rads (Si)	0.21Ω	12.5A
IRHY58230CM	1000K Rads (Si)	0.26Ω	12.5A

International Rectifier's R5™ technology provides high performance power MOSFETs for space applications. These devices have been characterized for Single Event Effects (SEE) with useful performance up to an LET of 80 (MeV/(mg/cm²)). The combination of low R_{Ds(on)} and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

Absolute Maximum Ratings

	Parameter		Units
I _D @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	12.5	A
I _D @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	8.0	
I _{DM}	Pulsed Drain Current ①	50	
P _D @ T _C = 25°C	Max. Power Dissipation	75	W
	Linear Derating Factor	0.6	W/°C
V _{GS}	Gate-to-Source Voltage	±20	V
E _{AS}	Single Pulse Avalanche Energy ②	60	mJ
I _{AR}	Avalanche Current ①	12.5	A
E _{AR}	Repetitive Avalanche Energy ①	7.5	mJ
dV/dt	Peak Diode Recovery dV/dt ③	4.4	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{TSG}	Storage Temperature Range		
	Lead Temperature	300 (0.063in./1.6mm from case for 10sec)	
	Weight	4.3 (Typical)	g



Features:

- Single Event Effect (SEE) Hardened
- Ultra Low R_{Ds(on)}
- Low Total Gate Charge
- Proton Tolerant
- Simple Drive Requirements
- Ease of Parallelizing
- Hermetically Sealed
- Ceramic Package
- Light Weight

Pre-Irradiation

For footnotes refer to the last page

Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	200	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 1.0\text{mA}$
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Temperature Coefficient of Breakdown Voltage	—	0.26	—	$\text{V}/^\circ\text{C}$	Reference to 25°C , $\text{I}_D = 1.0\text{mA}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source On-State Resistance	—	—	0.21	Ω	$\text{V}_{\text{GS}} = 12\text{V}, \text{I}_D = 8.0\text{A}$ ④
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	—	4.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 1.0\text{mA}$
g_{fs}	Forward Transconductance	10	—	—	S (Ω)	$\text{V}_{\text{DS}} > 15\text{V}, \text{I}_{\text{DS}} = 8.0\text{A}$ ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	10	μA	$\text{V}_{\text{DS}} = 160\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
		—	—	25		$\text{V}_{\text{DS}} = 160\text{V}, \text{V}_{\text{GS}} = 0\text{V}, T_j = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	$\text{V}_{\text{GS}} = 20\text{V}$
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		$\text{V}_{\text{GS}} = -20\text{V}$
Q_g	Total Gate Charge	—	—	50	nC	$\text{V}_{\text{GS}} = 12\text{V}, \text{I}_D = 12.5\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	7.4		$\text{V}_{\text{DS}} = 100\text{V}$
Q_{gd}	Gate-to-Drain ('Miller') Charge	—	—	20		
$t_{\text{d(on)}}$	Turn-On Delay Time	—	—	25	ns	$\text{V}_{\text{DD}} = 100\text{V}, \text{I}_D = 12.5\text{A}, \text{V}_{\text{GS}} = 12\text{V}, \text{R}_G = 7.5\Omega$
t_r	Rise Time	—	—	100		
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	—	35		
t_f	Fall Time	—	—	30		
$\text{L}_{\text{S}} + \text{L}_{\text{D}}$	Total Inductance	—	6.8	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C_{iss}	Input Capacitance	—	1043	—	pF	$\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = 25\text{V}$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	190	—		
Crss	Reverse Transfer Capacitance	—	20	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I_{S}	Continuous Source Current (Body Diode)	—	—	12.5	A	
I_{SM}	Pulse Source Current (Body Diode) ①	—	—	50		
V_{SD}	Diode Forward Voltage	—	—	1.2	V	$T_j = 25^\circ\text{C}, \text{I}_{\text{S}} = 12.5\text{A}, \text{V}_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	—	343	ns	$T_j = 25^\circ\text{C}, \text{I}_{\text{F}} = 12.5\text{A}, d\text{i}/dt \geq 100\text{A}/\mu\text{s}$
Q_{RR}	Reverse Recovery Charge	—	—	2.25	μC	$\text{V}_{\text{DD}} \leq 25\text{V}$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_{\text{S}} + \text{L}_{\text{D}}$.				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	1.67	$^\circ\text{C}/\text{W}$	
R_{thJA}	Junction-to-Ambient	—	—	80		

Note: Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

Radiation Characteristics

IRHY57230CM

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ $T_j = 25^\circ\text{C}$, Post Total Dose Irradiation^{⑤⑥}

	Parameter	Up to 600K Rads(Si) ¹				Units	Test Conditions
		Min	Max	Min	Max		
BV_{DSS}	Drain-to-Source Breakdown Voltage	200	—	200	—	V	$V_{\text{GS}} = 0\text{V}, I_D = 1.0\text{mA}$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	4.0	1.5	4.0		$V_{\text{GS}} = V_{\text{DS}}, I_D = 1.0\text{mA}$
I_{GSS}	Gate-to-Source Leakage Forward	—	100	—	100	nA	$V_{\text{GS}} = 20\text{V}$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100	—	-100		$V_{\text{GS}} = -20\text{V}$
I_{DSS}	Zero Gate Voltage Drain Current	—	10	—	10	μA	$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}$
$R_{\text{DS(on)}}$	Static Drain-to-Source ^④ On-State Resistance (TO-3)	—	0.215	—	0.265	Ω	$V_{\text{GS}} = 12\text{V}, I_D = 8.0\text{A}$
$R_{\text{DS(on)}}$	Static Drain-to-Source ^④ On-State Resistance (TO-257AA)	—	0.21	—	0.26	Ω	$V_{\text{GS}} = 12\text{V}, I_D = 8.0\text{A}$
V_{SD}	Diode Forward Voltage ^④	—	1.2	—	1.2	V	$V_{\text{GS}} = 0\text{V}, I_S = 12.5\text{A}$

1. Part numbers IRHY57230CM, IRHY53230CM and IRHY54230CM

2. Part number IRHY58230CM

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Single Event Effect Safe Operating Area

Ion	LET MeV/(mg/cm ²)	Energy (MeV)	Range (μm)	V_{DS} (V)				
				@ $V_{\text{GS}} = 0\text{V}$	@ $V_{\text{GS}} = -5\text{V}$	@ $V_{\text{GS}} = -10\text{V}$	@ $V_{\text{GS}} = -15\text{V}$	@ $V_{\text{GS}} = -20\text{V}$
Br	36.7	309	39.5	200	200	150	150	50
I	59.4	341	32.5	200	200	40	35	30
Au	82.3	350	28.4	50	35	25	—	—

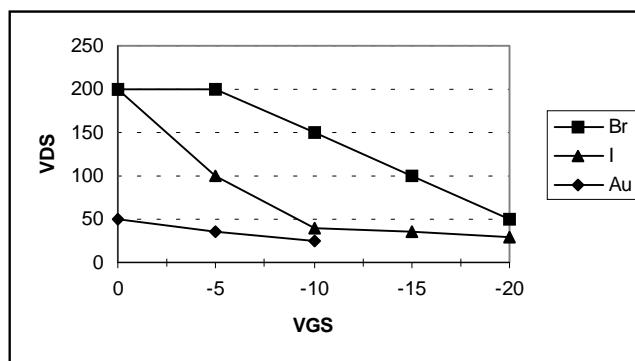


Fig a. Single Event Effect, Safe Operating Area

For footnotes refer to the last page

IRHY57230CM

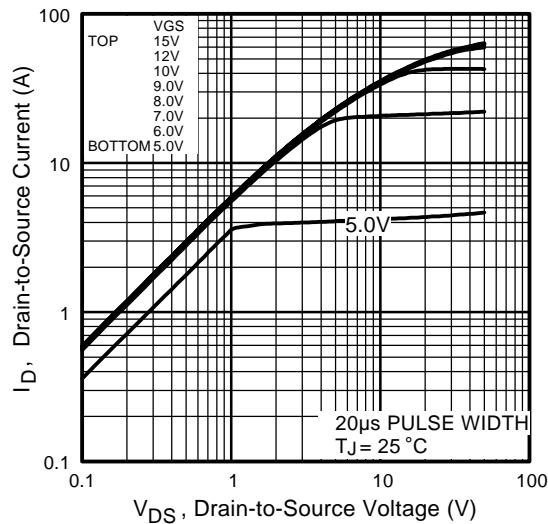


Fig 1. Typical Output Characteristics

Pre-Irradiation

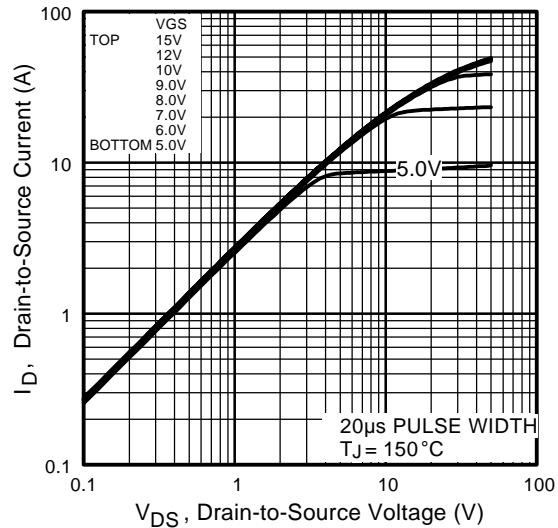


Fig 2. Typical Output Characteristics

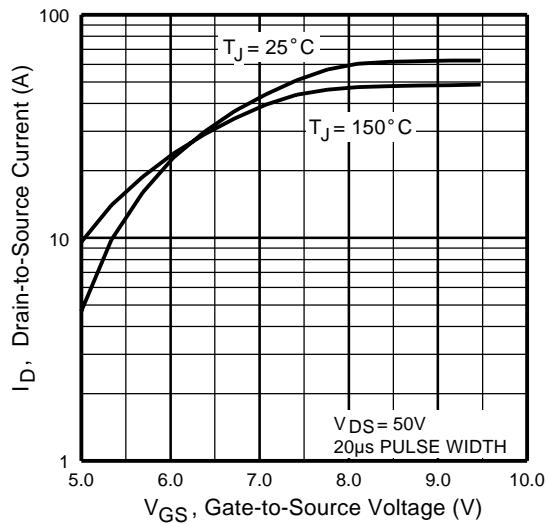


Fig 3. Typical Transfer Characteristics

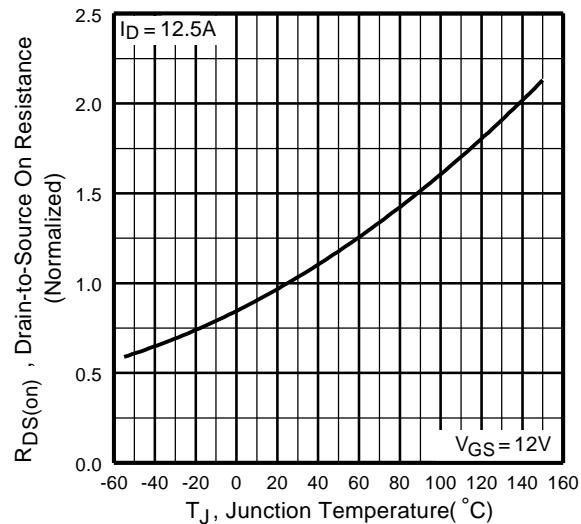


Fig 4. Normalized On-Resistance Vs. Temperature

Pre-Irradiation

IRHY57230CM

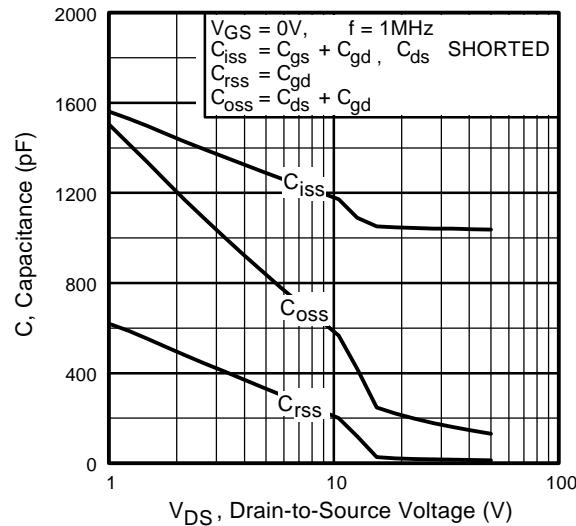


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

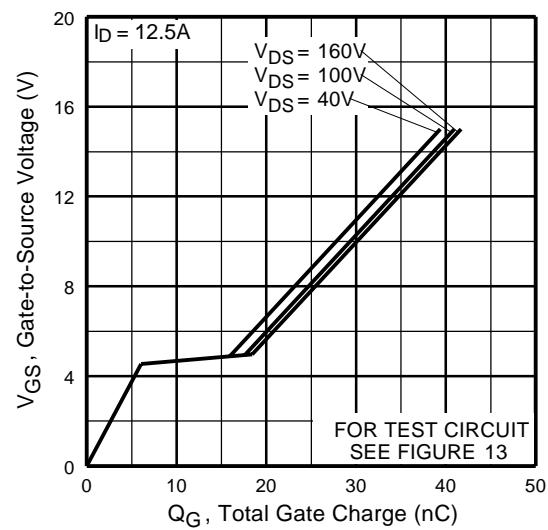


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

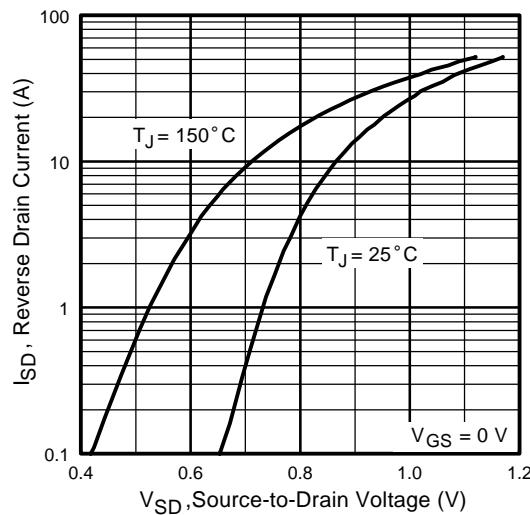


Fig 7. Typical Source-Drain Diode
Forward Voltage

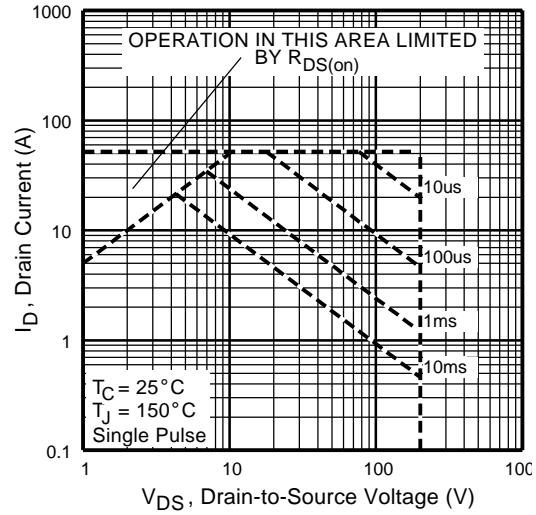


Fig 8. Maximum Safe Operating Area

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Pre-Irradiation

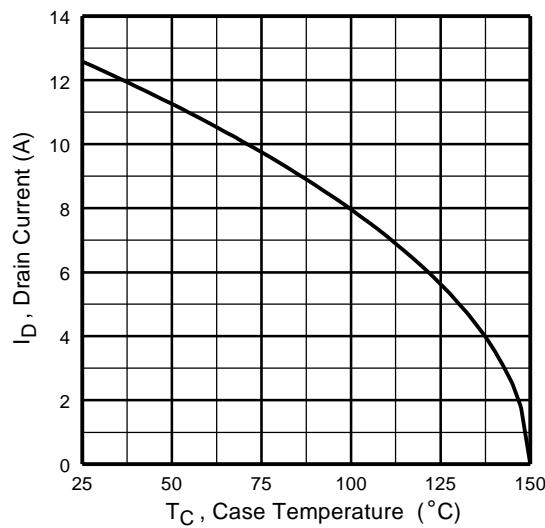


Fig 9. Maximum Drain Current Vs.
Case Temperature

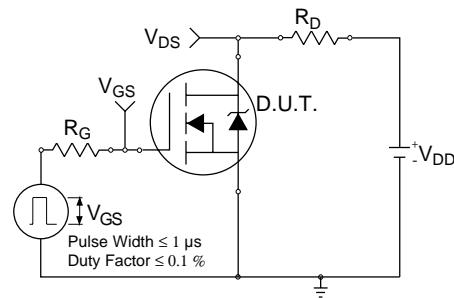


Fig 10a. Switching Time Test Circuit

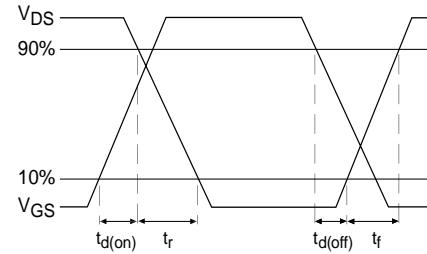


Fig 10b. Switching Time Waveforms

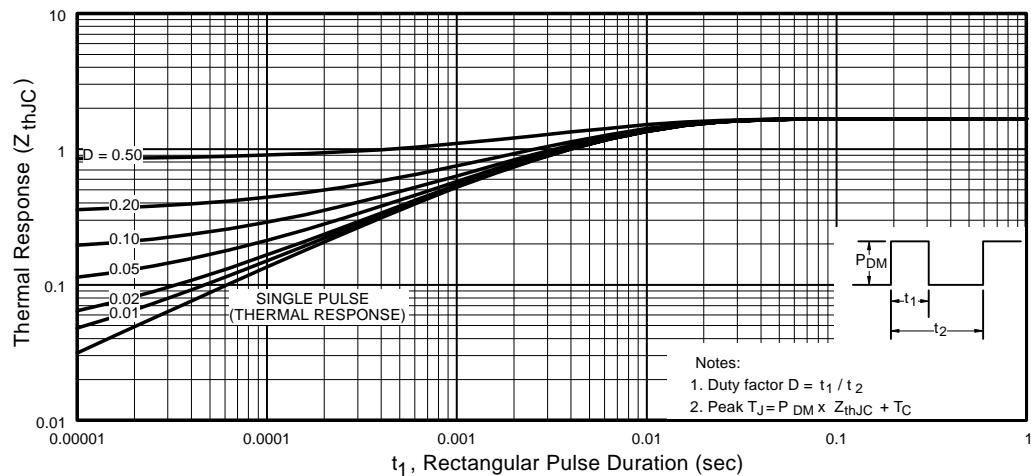


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Pre-Irradiation

IRHY57230CM

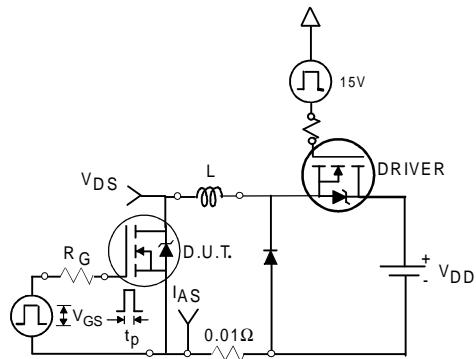


Fig 12a. Unclamped Inductive Test Circuit

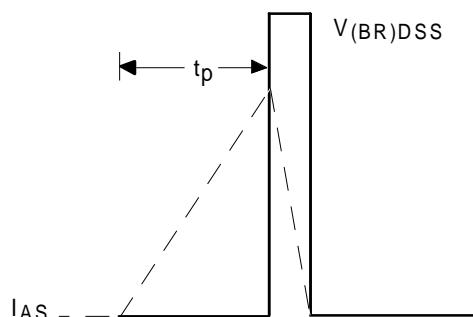


Fig 12b. Unclamped Inductive Waveforms

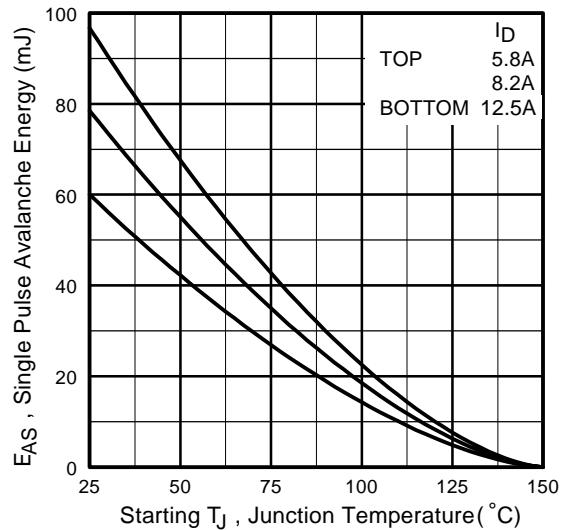


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

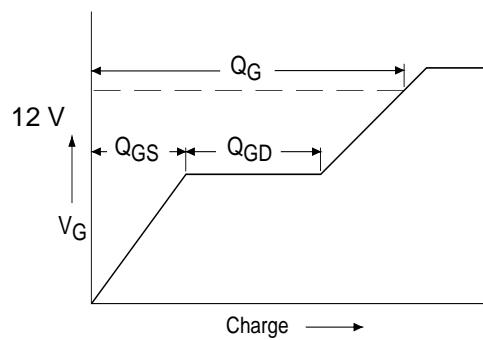


Fig 13a. Basic Gate Charge Waveform

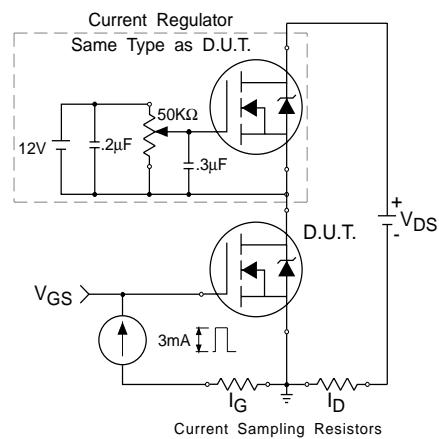
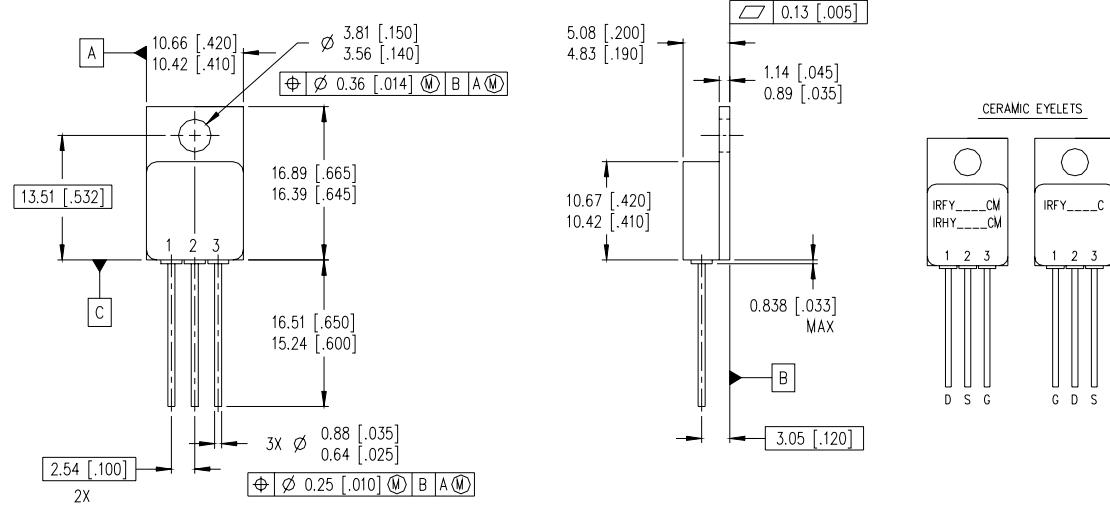


Fig 13b. Gate Charge Test Circuit

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② V_{DD} = 50V, starting T_J = 25°C, L = 0.67 mH
Peak I_L = 12.5A, V_{GS} = 12V
- ③ ISD ≤ 12.5A, di/dt ≤ 274A/μs,
V_{DD} ≤ 200V, T_J ≤ 150°C

- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
160 volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — TO-257AA**NOTES:**

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-257AA.

LEGEND
D – DRAIN
S – SOURCE
G – GATE

International
IR Rectifier

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